



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Ching-Fa YEH et al.

Group Art Unit: 2814

Serial No: 10/075,293

Examiner: H. Trinh

Filed: February 15, 2002

For: METHOD OF REDUCING THICK FILM STRESS OF SPIN-ON DIELECTRIC
AND THE RESULTING SANDWICH DIELECTRIC STRUCTURE

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of March 13, 2003. Please amend the
above-identified application as follows:

Amendments to the claims are reflected in the listing of claims which begins on
page 2 of this paper.

Remarks begin on page 6 of this paper.

S/B
6-17-03
J. Arturi

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JUN 16 2003
TECHNOLOGY CENTER 2800